

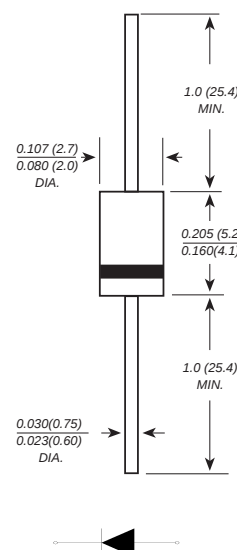
Features

The plastic package carries Underwriters Laboratory
Flammability Classification 94V-0
Open Junction chip
Low reverse leakage
High forward surge current capability
High temperature soldering guaranteed
260°C/10 seconds at terminals

Mechanical Data

Case : Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.0088 ounce, 0.25 grams

DO-41



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz,resistive or inductive load,
for capacitive load current derate by 20%.

Parameter	SYMBOLS	UF4007	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC blocking voltage	V_{DC}	1000	V
Maximum average forward rectified current at $T_L=100^{\circ}C$	$I_{(AV)}$	1.0	A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	30.0	A
Maximum instantaneous forward voltage at 1.0A	V_F	1.7	V
Maximum DC reverse current $T_A=25^{\circ}C$ at rated DC blocking voltage $T_A=100^{\circ}C$	I_R	5.0 200	μA
Maximum reverse recovery time(Note 1)	T_{rr}	75	ns
Typical junction capacitance (Note2)	C_j	25.0	pF
Typical thermal resistance	R_{qJA}	65.0	$^{\circ}C/W$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150	$^{\circ}C$

Note: 1.Reverse recovery time test condition: $I_F=0.5A$ $I_R=1.0A$ $I_{rr}=0.25A$
2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

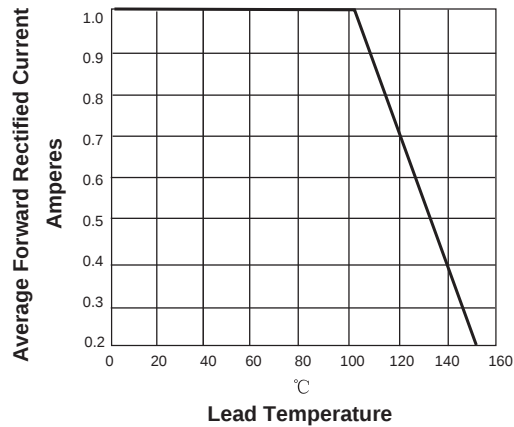


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG

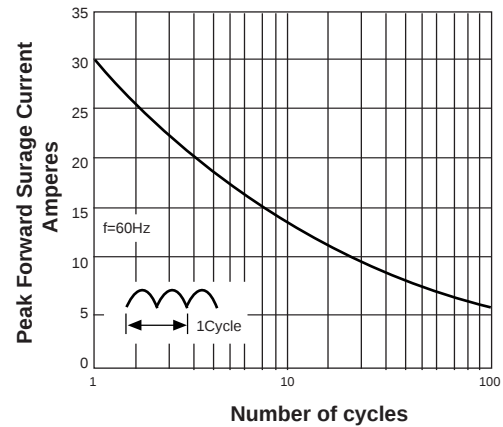


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

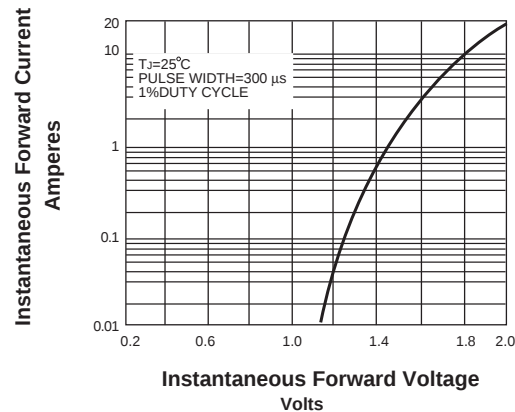
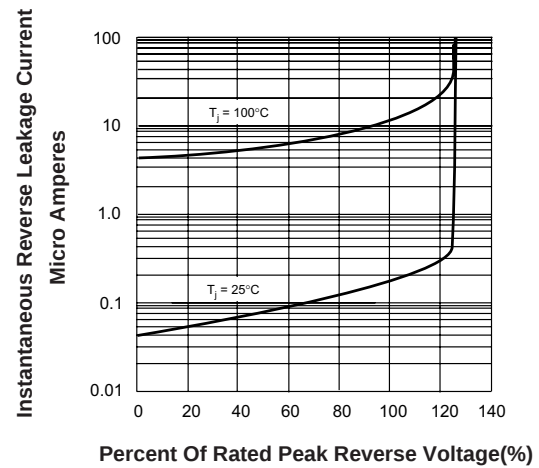
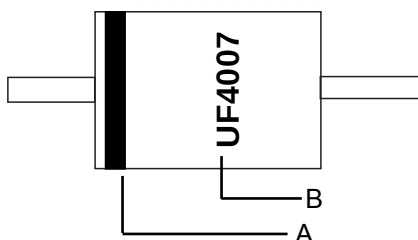


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

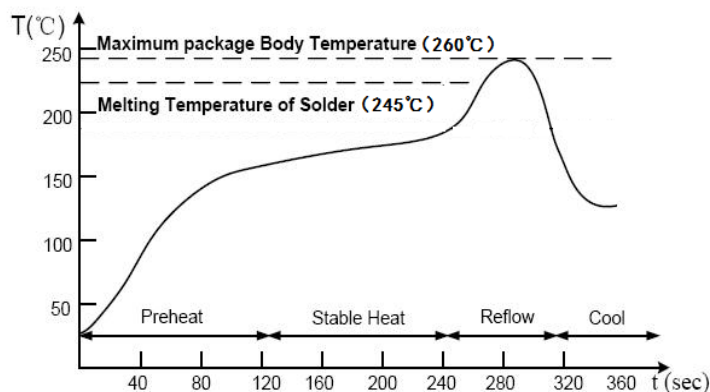


Marking



Symbol	Explanation
A	Color Band Denotes Cathode
B	Product Name

Suggested Soldering Temperature Profile

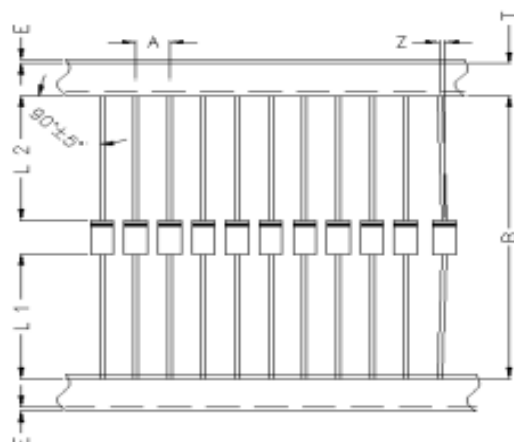


Note

Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
 The device can be exposed to a maximum temperature of 260°C for 10 seconds.
 Devices can be cleaned using standard industry methods and solvents.
 If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Taping Specifications



Item	Symbol	Specifications(mm)
Component Pitch	A	5.0±0.5
Inner Tape Pitch	B	52.4±1.5
Component alignment	Z	1.2 Max
Tape width	T	6.0±0.5
Exposed adhesive	E	0.8 Max
Body eccentricity	L1-L2	1.0 Max

Ammunition Package Specifications

Package	Inner Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
DO - 41	255*150*75	5	420*276*312	50

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